

# New Product Introduction



December 2025



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# 1ED301xMC12I single-channel isolated gate driver IC with opto-emulator

Heatmap indicator				
AMERICAS	JAPAN	GC	AP	EMEA

5.7 kV (rms) single-channel gate driver IC with reinforced isolation, 6.5 A output current, opto-emulator input, UVLOs for Si, IGBT, SiC.



### Features

- > Up to 2300 V switches
- > 2300 V functional offset voltage capable
- > Galvanically isolated coreless transformer
- > 35 V absolute maximum output supply voltage
- > 5.5 to 15 mA input diode forward current
- > CTI 600 package with 8 mm creepage
- > Pin-to-pin with opto devices on market
- > Opto-compatible input

### Benefits

- > -18 V maximum reverse input V
- > IEC 60747-17 (planned), UL 1577
- >  $V_{ORM} = 1767$  V (peak, reinforced)
- >  $V_{ISO} = 6.84$  kV (rms) for 1 second
- >  $V_{ISO} = 5.7$  kV (rms) for 1 min
- > UVLO options for Si, IGBT, SiC

### Competitive advantage

- > Best-in-class propagation delay of 40 ns
- > Strong 6.5 A / 6 A output stage
- > Best-in-class CMTI of > 300 kV/ $\mu$ s
- > 10 ns max part-to-part propagation delay skew

### Target applications

- > Battery energy storage (BESS)
- > EV charging
- > DIN rail power supply solutions
- > General purpose motor drive
- > Photovoltaic
- > Motor control

### Product collaterals / Online support

[Product family page](#)

### Product overview incl. datasheet link

OPN	SP Number	Package
<a href="#">1ED3010MC12IXUMA1</a>	SP006104460	PG-LDSO-6
<a href="#">1ED3011MC12IXUMA1</a>	SP006104507	PG-LDSO-6
<a href="#">1ED3012MC12IXUMA1</a>	SP006104509	PG-LDSO-6

## CoolSiC™ MOSFET 1400 V G2 in TO-247PLUS-4 Reflow package

Heatmap indicator				
AMERICAS	JAPAN	GC	AP	EMEA

The CoolSiC™ MOSFET 1400 V G2 in a TO-247PLUS-4 Reflow package is now also available in 6 mΩ, 11 mΩ, 24 mΩ, and 29 mΩ  $R_{DS(on)}$  variants, ideal for high-output power applications such as EV charging, ESS, CAV and other applications.

The CoolSiC™ MOSFET 1400 V G2 technology is a cutting-edge technology offering improved thermal performance, increased power density, and enhanced reliability. The package enables reflow soldering assembly (3x reflow soldering possible) enabling lower thermal resistance and supports high peak currents.



### Features

- > Very low switching losses
- > Package backside suitable for reflow soldering at 260°C, 3 times
- > Overload operation up to  $T_{vj} = 200^{\circ}\text{C}$
- > Short circuit withstand time 2 μs
- > Benchmark gate threshold voltage,  $V_{GS(th)} = 4.2\text{ V}$
- > Robust against parasitic turn on, 0 V turn-off gate voltage can be applied
- > Robust body diode for hard commutation
- > .XT interconnection technology for best-in-class thermal performance
- > Wide power pins (2 mm) for high current capability
- > Resistive weldable pins for direct busbar connections
- > TO-247PLUS package with high creepage distance 10.8 mm and  $CTI \geq 600\text{ V}$

### Benefits

- > Increased power density
- > Increased system output power
- > Improved overall efficiency
- > Robustness against transient overloads, avalanche condition and Miller effect
- > Ease of system design against overcurrent events
- > Easy paralleling

### Competitive advantage

- > Enabling designs >1000 V
- > Reflow soldering assembly – lower thermal resistance
- > For applications with an upper limit of 1000 volts -> sufficient voltage margins for faster switching at high peak currents
- > Its high-power density allows reducing the overall system size

### Target applications

- > Commercial, construction and agricultural vehicles (CAV)
- > EV charging
- > Energy storage systems (ESS)
- > Online UPS / Industrial UPS
- > String inverter
- > General purpose drives (GPD)

### Product collaterals / Online support

[Product family page](#)

### Product overview incl. datasheet link

OPN	SP Number	Package
<a href="#">IMYR140R006M2HXL SA1</a>	SP005931431	PG-TO247-4
<a href="#">IMYR140R011M2HXL SA1</a>	SP005931436	PG-TO247-4
<a href="#">IMYR140R024M2HXL SA1</a>	SP005962806	PG-TO247-4
<a href="#">IMYR140R029M2HXL SA1</a>	SP005962808	PG-TO247-4

# EconoPACK™ 3 portfolio for 300 kW+ utility-scaled PV inverter

Heatmap indicator				
AMERICAS	JAPAN	GC	AP	EMEA

EconoPACK™ 3B, 950 V, 600 A in 3-level NPC1 topology featuring SiC diode, 950 V TRENCHSTOP™ IGBT7 S7 and 1200 V IGBT7;  
EconoPACK™ 3B, 950 V, 400 A in 3-level boost topology featuring SiC diode and 950 V TRENCHSTOP™ IGBT7 S7.



### Features

- > TRENCHSTOP™ IGBT7
- > Well established Econo3 package
- > Integrated NTC temperature sensor
- > CoolSiC™ Schottky diode

### Benefits

- > Easy to design
- > Low switching losses
- > Enables higher output power up to 320 kW
- > High power density in EconoPACK™ 3B package with baseplate
- > Outstanding module efficiency which enables system cost advantages

### Competitive advantage

- > Compact design
- > High robustness against LVRT and HVRT
- > High efficiency with latest SiC technology
- > Overload capabilities up to 150°C
- > Ideal choice for 1500 Vdc 320 kW utility PV

### Target applications

- > Solar

### Product collaterals / Online support

[Product family page](#)

### Product overview incl. datasheet link

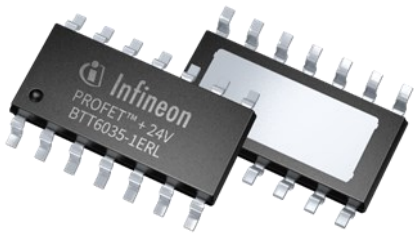
OPN	SP Number	Package
<a href="#">F3L600R10N3S7FBPSA1</a>	SP005904227	AG-ECONO3B-7011
<a href="#">F3L400R10N3S7FC1BPSA1</a>	SP006029174	AG-ECONO3B-7011

# PROFET™ + 24 V BTT6035-1ERL smart power high-side switch

Heatmap indicator				
AMERICAS	JAPAN	GC	AP	EMEA

The BTT6035-1ERL, as part of the ISO 26262-ready PROFET™ + 24 V family, features an inbuilt adjustable overcurrent limitation for safeguarding sensitive loads and supply line wires from abnormal currents.

This 35 mΩ single-channel device is fitted for switching large capacitive loads. It comes in a TDSO-14 package and is footprint compatible with family members, offering protection and diagnostic functions for itself, attached loads and power net.



## Features

- > R<sub>DS(on)</sub> of 35 mΩ (typical)
- > Up to 48 V operating voltage
- > 1 channel
- > Adjustable current limitation
- > Capacitive load switching
- > PRO-SIL™ ISO 26262-ready

## Benefits

- > Flexible current limit thresholds
- > Allows safe switching of big capacitors
- > No external pre-charge circuit
- > Protect load supply line wires
- > Supporting evaluation acc. to ISO 26262

## Competitive advantage

- > Adjustable current limitation
- > PRO-SIL™ ISO 26262-ready
- > Footprint compatible with PROFET™ + 24 V
- > Tested for extended lifetime conditions for commercial, construction and agricultural vehicles

## Target applications

- > Commercial, construction and agricultural vehicles (CAV)
- > Body control module for 24 V commercial vehicles and industrial vehicles
- > Replaces electromechanical relays, fuses, and discrete circuits in 24 V power net

## Product collaterals / Online support

[Product family page](#)

## Product overview incl. datasheet link

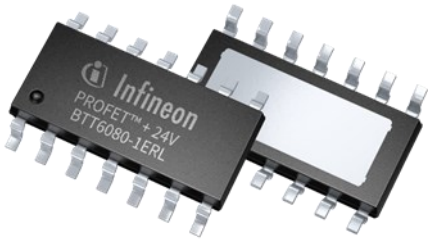
OPN	SP Number	Package
<a href="#">BTT60351ERLXUMA1</a>	SP005564068	PG-TDSO-14

# PROFET™ + 24 V BTT6080-1ERL smart power high-side switch

Heatmap indicator				
AMERICAS	JAPAN	GC	AP	EMEA

The BTT6080-1ERL, as part of the ISO 26262-ready PROFET™ + 24 V family, features an inbuilt adjustable overcurrent limitation for safeguarding sensitive loads and supply line wires from abnormal currents.

This 80 mΩ single-channel device is fitted for switching large capacitive loads. It comes in a TDSO-14 package and is footprint compatible with family members, offering protection and diagnostic functions for itself, attached loads and power net.



## Features

- >  $R_{DS(on)}$  of 80 mΩ (typical)
- > Up to 48 V operating voltage
- > 1 channel
- > Adjustable current limitation
- > Capacitive load switching
- > PRO-SIL™ ISO 26262-ready

## Benefits

- > Flexible current limit thresholds
- > Allows safe switching of big capacitors
- > No external pre-charge circuit
- > Protect load supply line wires
- > Supporting evaluation acc. to ISO 26262

## Competitive advantage

- > Adjustable current limitation
- > PRO-SIL™ ISO 26262-ready
- > Footprint compatible with PROFET™ + 24 V
- > Tested for extended lifetime conditions for commercial, construction and agricultural vehicles

## Target applications

- > Commercial, construction and agricultural vehicles (CAV)
- > Body control module for 24 V commercial vehicles and industrial vehicles
- > Replaces electromechanical relays, fuses, and discrete circuits in 24 V power net

## Product collaterals / Online support

[Product family page](#)

## Product overview incl. datasheet link

OPN	SP Number	Package
<a href="#">BTT60801ERLXUMA1</a>	SP005564070	PG-TDSO-14

## CoolSiC™ MOSFET discrete 1200 V G2 in top-side cooled Q-DPAK package

Heatmap indicator				
AMERICAS	JAPAN	GC	AP	EMEA

The CoolSiC™ MOSFET discrete 1200 V G2 in top-side cooled Q-DPAK single-switch package is now available in 4 mΩ and 5 mΩ  $R_{DS(on)}$  variants. It is specifically designed for a wide use in industrial applications, including EV charging, solar, UPS, SSCB, industrial drives, AI and CAV.



The Q-DPAK provides customers with a reduced system cost by enabling easier assembly with outstanding thermal performance. Compared to bottom-side cooled solutions, top-side cooled devices enable a more optimized PCB layout, which in turn reduces the effects of parasitic components and stray inductances, while also providing enhanced thermal management capabilities.

Features	Benefits
<ul style="list-style-type: none"><li>&gt; SMD top-side-cooled package</li><li>&gt; Low stray inductance</li><li>&gt; CoolSiC™ MOSFET 1200 V G2 technology with enhanced switching performance and FOM factor</li><li>&gt; .XT interconnection technology</li><li>&gt; Lowest <math>R_{DS(on)}</math></li><li>&gt; Mold compound (CTI &gt; 600) and mold groove (CD &gt; 4.8 mm)</li><li>&gt; Humidity robustness</li><li>&gt; Avalanche robust, short-circuit and PTO</li></ul>	<ul style="list-style-type: none"><li>&gt; Higher power density</li><li>&gt; Enable automated assembly</li><li>&gt; Less complex designs needed</li><li>&gt; Outstanding thermal performance compared to BSC packages</li><li>&gt; Improve system power losses</li><li>&gt; Enable a <math>V_{RMS}</math> of 950 V with pollution degree 2</li><li>&gt; High reliability</li><li>&gt; Lower TCO cost or BOM cost</li></ul>
Competitive advantage	Target applications
<ul style="list-style-type: none"><li>&gt; Increased power density</li><li>&gt; Improved the thermal performance compared to BSC devices</li><li>&gt; Enables easier electrical design</li></ul>	<ul style="list-style-type: none"><li>&gt; EV charging</li><li>&gt; Solar</li><li>&gt; UPS</li><li>&gt; SSCB</li><li>&gt; Industrial drives</li><li>&gt; AI</li><li>&gt; CAV</li></ul>

### Product collaterals / Online support

[Product family page](#)

### Product overview incl. datasheet link

OPN	SP Number	Package
<a href="#">IMCQ120R004M2HXUMA1</a>	SP006139015	PG-HDSOP-22
<a href="#">IMCQ120R005M2HXUMA1</a>	SP006139016	PG-HDSOP-22

## CoolSiC™ MOSFET M1H common source 62 mm

Heatmap indicator				
AMERICAS	JAPAN	GC	AP	EMEA

62 mm CoolSiC™ MOSFET half bridge module 1200 V and 2000 V in the well known 62 mm housing combined with M1H chip technology. Now also available with common source configuration.



### Features

- > Robust integrated body diode and thus optimal thermal conditions
- > Highest robustness against humidity
- > Superior gate oxide reliability
- > High cosmic ray robustness

### Benefits

- > Optimized use under demanding conditions
- > Lower voltage overshoot
- > Minimized conduction losses
- > High speed switching with very low losses
- > Symmetrical module design and switching behavior of upper and lower switch
- > Standard module construction technique secures known reliable
- > Production in the 62 mm high volume production line

### Competitive advantage

- > Common source configuration
- > Lowest  $R_{DS(on)}$
- > Highest  $V_{GS(th)}$

### Target applications

- > Energy Storage Systems
- > EV charging
- > Photovoltaic
- > Solid State Circuit Breaker

### Product collaterals / Online support

[Product family page](#)

### Product overview incl. datasheet link

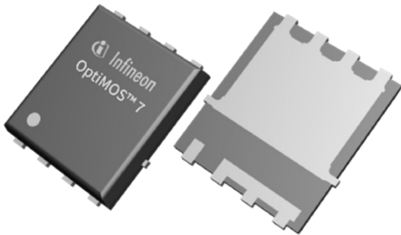
OPN	SP Number	Package
<a href="#">FF1MR12KM1HSHPSA1</a>	SP005976111	AG-62MMHB-3111
<a href="#">FF3MR12KM1HSHPSA1</a>	SP005976714	AG-62MMHB-3111
<a href="#">FF5MR20KM1HSHPSA1</a>	SP005855022	AG-62MMHB-3111



# OptiMOS™ 7 n-channel power MOSFET 80 V in SSO8 package

Heatmap indicator				
AMERICAS	JAPAN	GC	AP	EMEA

The OptiMOS™ 7 technology features application-optimized power MOSFETs to meet the requirements of specific applications. The ISC019N08NM7 is a normal level 80 V MOSFET in SuperSO8 packaging with 1.9 Ω on-resistance.



### Features

- > Very low on-resistance
- > High current carrying capability
- > Industrial qual for optimum reliability
- > Industry-standard footprint

### Benefits

- > Low conduction losses
- > Highest efficiency and power density
- > High system reliability
- > Thermal robustness

### Competitive advantage

- > Very low  $R_{DS(on)}$
- > Good price/performance ratio
- > High-efficiency MOSFET technology

### Target applications

- > Data center and AI data center solutions
- > Telecommunications infrastructure
- > Industrial and consumer BMS
- > Server power supply units (PSU)

### Product collaterals / Online support

[Product page](#)

### Product overview incl. datasheet link

OPN	SP Number	Package
<a href="#">ISC019N08NM7ATMA1</a>	SP006166279	PG-TDSON-8

## XENSIV™ KP467Q air pressure sensor

Heatmap indicator				
AMERICAS	JAPAN	GC	AP	EMEA

KP467Q is besides KP467 the first pressure sensor for battery management systems that monitors and provides a warning in case of a thermal runaway event with highest efficiency, immediate response and very cost-effectively. The lower minimum LPM threshold is tailored to the recently widely used LFP battery types.



### Features

- > Autonomous low-power monitoring modes
- > LPM threshold optimized for LFP battery
- > Automotive qualification
- > Measuring pressure and IC temperature
- > High accuracy and reliability
- > Advanced diagnostic functions
- > High and flexible resolution output
- > Small package
- > Backwards compatible to existing BAP

### Benefits

- > Robust battery failure monitoring
- > Battery power savings while parking
- > Easy design-in into safety system
- > Robust sensors failure detection
- > Robust system
- > Maximum system efficiency
- > Best fitting configuration
- > Minimized design in efforts
- > Reuse of basic PCB layout and SW
- > High quality solution

### Competitive advantage

- > Optimized LPM (low-power-monitoring mode) threshold for LFP batteries in xEVs
- > Best in class on absolute and relative pressure accuracy
- > Supply voltage domains for 3.3 V and 5 V
- > Live pressure reading via SPI in on mode with max 250 kHz pressure update
- > Package with visible leads + LTI flanks for lead tip inspection

### Target applications

- > Thermal Runaway detection in battery management systems for xEVs
- > Automotive battery management system (BMS) - 12 V to 24 V
- > Automotive battery management system (BMS) - 48 V
- > Automotive battery management system (BMS) - high-voltage

### Product collaterals / Online support

[Product page](#)

### Product overview incl. datasheet link

OPN	SP Number	Package
<a href="#">KP467QXTMA1</a>	SP006179846	PG-DFN-8

## EZ-USB™ FX2G3 USB 2.0 controllers

Heatmap indicator				
AMERICAS	JAPAN	GC	AP	EMEA

Infineon's EZ-USB™ FX2G3 is a family of highly-integrated USB 2.0 controllers serving as the basis for any 480 Mbps USB peripheral device.

With dual-core ARM® Cortex® architecture, USB-C integration, broad compatibility for serial interfaces, cryptographic-engine, and comprehensive development support, EZ-USB™ FX2G3 is the one-stop solution for USB 2.0 connectivity – enabling enhanced processing, security and scalable data rates in consumer electronics, biometrics, and medical-healthcare and camera applications.



### Features

- > USB 2.0 high speed (480 Mbps)
- > Up to 32 configurable endpoints
- > ARM® Cortex®-M4F and Cortex®-M0+
- > 1024 + 128 KB SRAM, 512 KB flash
- > Integrated USB-C Mux
- > Crypto engine: AES, DES, SHA, RSA
- > QSPI, SPI, UART, CAN and I2C support
- > Compact 8 x 8 mm 104-LGA package
- > Dedicated SW development platform

### Benefits

- > Build secure systems
- > Customer solutions with programmability
- > Flexible interfaces
- > Fast time to market
- > Ideal for secure USB communication

### Competitive advantage

- > EZ-USB™ FX2G3 offers a powerful competitive advantage with USB 2.0 HS speed and 32 configurable endpoints, a high-performance GPIF III interface (16-bit, 100 MHz), and 1 MB dedicated USB buffer memory.
- > Its robust security features, ultra-low power modes, flexible clocking options, and the comprehensive ModusToolbox™ development ecosystem ensure efficiency, security, and seamless application integration.

### Target applications

- > Biometrics
- > Medical and healthcare
- > Camera applications
- > Industrial automation
- > Consumer electronics
- > Robotics
- > Security

### Product collaterals / Online support

[Product family page](#)

### Product overview incl. datasheet link

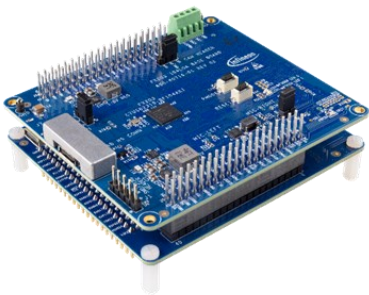
OPN	SP Number	Package
<a href="#">CYUSB2315BF104AXIXQMA1</a>	SP006088682	PG-VFLGA-104
<a href="#">CYUSB2316BF104AXIXQMA1</a>	SP006088686	PG-VFLGA-104
<a href="#">CYUSB2317BF104AXIXQMA1</a>	SP006088717	PG-VFLGA-104
<a href="#">CYUSB2318BF104AXIXQMA1</a>	SP006088721	PG-VFLGA-104

## EZ-USB™ FX2G3 development kit

Heatmap indicator				
AMERICAS	JAPAN	GC	AP	EMEA

EZ-USB™ FX2G3 development kit (KIT\_FX2G3\_104LGA) is a versatile USB 2.0 development kit designed for fast prototyping of high-speed data, multimedia, and industrial applications. It supports video and audio streaming, flexible power options, and expandable functionality with an included FPGA add-on board.

Ideal for USB-enabled designs, it accelerates product development in diverse applications, ranging from consumer electronics to embedded systems, with seamless peripheral integration and robust connectivity options.



### Features

- > High-speed USB 2.0 data transfer
- > Enhanced multimedia support
- > Integrated CAN transceiver
- > Highly flexible power operation
- > Modular and expandable design

### Benefits

- > Accelerates product development process
- > Supports multimedia applications
- > Improved cost and power efficiency
- > Scalable hardware platform with FPGA

### Competitive advantage

- > EZ-USB™ FX2G3 offers a powerful competitive advantage with USB 2.0 HS speed and 32 configurable endpoints, a high-performance GPIF III interface (16-bit, 100 MHz) and 1 MB dedicated USB buffer memory.
- > Its robust security features, ultra-low power modes, flexible clocking options and the comprehensive ModusToolbox™ development ecosystem ensure efficiency, security and seamless application integration

### Target applications

- > Biometrics
- > Medical and healthcare
- > Camera applications
- > Industrial automation
- > Consumer electronics
- > Robotics
- > Security

### Product collaterals / Online support

[Board page](#)

### Product overview incl. user guide link

OPN	SP Number
<a href="#">KITFX2G3104LGATOB01</a>	SP006090296

# Turnkey-ready 150W water pump reference design with MOTIX™ MCU TLE995x and OptiMOS™ 7 40 V MOSFETs

Heatmap indicator				
AMERICAS	JAPAN	GC	AP	EMEA

Infineon’s 150W water pump reference design (REF\_WATERPUMP150W) is a turnkey-ready motor control solution with pre-tested block commutation and Field-Oriented Control (FOC) software and proven hardware featuring MOTIX™ TLE9954EQW40 32-bit motor control SoC and OptiMOS™ 7 40 V MOSFETs in half-bridge configuration; moreover, intuitive evaluation tools for rapid development. For applications requiring customized or advanced functionalities, Infineon partners with MOTEON offering tailored application software and expertise to meet your requirements and speed time-to-market.

MOTIX™ TLE9954EQW40 is an automotive qualified (AEC Q-100, Grade 0) single-chip 3-phase motor driver based on Arm® Cortex®-M23. The system-on-chip (SoC) comes with Field Oriented Control (FOC) capability, is ISO 26262-compliant (ASIL B) and integrates Arm® TrustZone®.

## Features

- > MOTIX™TLE9954EQW40 32-bit motor control SoC
- > Latest OptiMOS™ 7 40 V half-bridge MOSFETs in SSO8, IAUCN04S7N024H
- > Latest OptiMOS™ 7 40 V MOSFET in S3O8, IAUZN04S7N032
- > Reference for EMC
- > Reference for thermal performance
- > SWD port for debug connection
- > LIN port
- > Extensive documentation

## Competitive advantage

- > Compact, scalable and robust design
- > Fast time to market
- > Easy design-in
- > Optimized BOM
- > Comprehensive ecosystem support

## Product collaterals / Online support

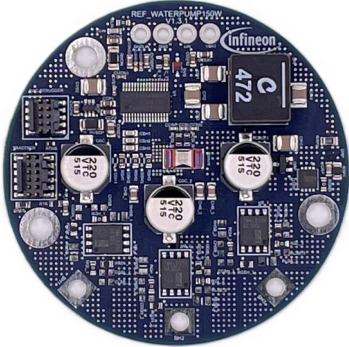
[Board page](#)

## Benefits

- > Reduced time to market
- > Small PCB size with compact design
- > System cost saving through integration
- > ASIL B certified safe motor operation
- > Premium design-in experience

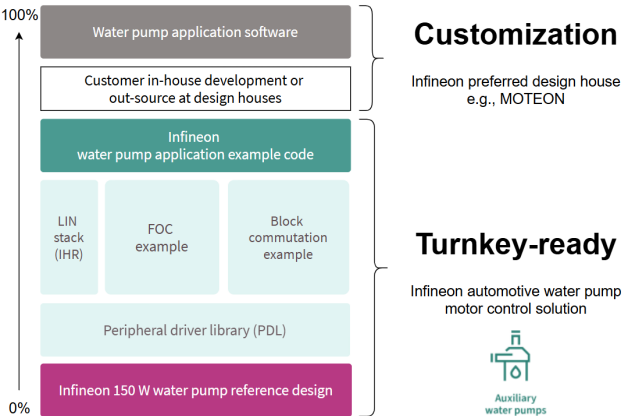
## Target applications

- > Water pump



## Block diagram

- > Turnkey-ready system solution offering



## Product overview incl. user guide link

OPN	SP Number	Package
<a href="#">REFWATERPUMP150WTOBO1</a>	SP006022127	L-MADK-1

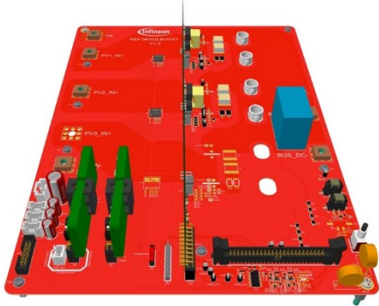
# REF\_9KW2LBOOST

## 9 kW 2-level boost converter for solar photovoltaic solutions

Heatmap indicator				
AMERICAS	JAPAN	GC	AP	EMEA

The reference board is a 2-channel boost converter designed to handle power levels up to 9 kW that features Infineon's CoolSiC™ Schottky diode IDS20G65C5 and XENSIV™ magnetic current sensor.

Its high switching frequency reduces size and cost. Additionally, the PCB offers all traces for a third channel and provides connectors for users to integrate their own passive components.



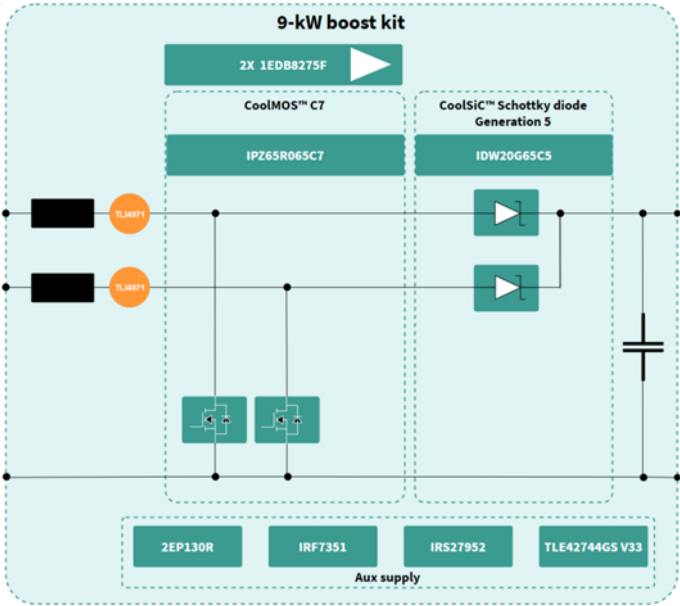
### Features

- > Isolated gate driver card
- > Current sensors for each DC input
- > Large heat sink for passive cooling
- > Fans for high power rating
- > Built-in auxiliary power supply card

### Benefits

- > High switching frequency of 24 kHz
- > Fast and uncomplicated testing
- > Blueprint for shorter time to market

### Block diagram



### Target applications

- > Photovoltaic

### Product collaterals / Online support

[Board page](#)

### Product overview incl. user guide link

OPN	SP Number
<a href="#">REF9KW2LBOOSTTOBO1</a>	SP006182019

# EVAL-M1-IM06B50 Evaluation board for CIPOS™ Mini IPM

Heatmap indicator				
AMERICAS	JAPAN	GC	AP	EMEA

This evaluation board is a complete power stage, powered by IM06B50GC1 CIPOS™ Mini 600 V 50 A, equipped with MADK™ M1 20-pin interface connector to be used with the matching iMOTION™ MADK Control boards. It is recommended to use in the systems based on 100-230 V AC mains voltage up to 5000 W inverter board output power with active cooling.



### Features

- > Ready to use three-phase inverter
- > Output power up to 5000 W
- > On-board EMI filter and pass EMI standards EN55032
- > Over current/temperature protection RoHS compliant

### Benefits

- > Evaluate CIPOS™ Mini IM06B50GC1 IPM module for your application
- > Get your motor running within one hour in combination with iMOTION™ MADK control boards
- > Understand more about motor control in high voltage domain

### Competitive advantage

- > Broad application coverage thanks to excellent power loss and thermal performance
- > Excellent system level size reduction with enhanced power density in a compact package platform

### Target applications

- > Heating ventilation and air conditioning (HVAC)
- > Residential AC
- > Industrial drives

### Product collaterals / Online support

[Board page](#)

### Product overview incl. user guide link

OPN	SP Number
<a href="#">EVALM1IM06B50TOBO1</a>	SP006136968

## AURIX™ Configuration Studio

Heatmap indicator				
AMERICAS	JAPAN	GC	AP	EMEA

The AURIX™ Configuration Studio is an innovative solution is designed to make development easier, faster, and more efficient for engineers working with AURIX™ devices.

By providing an intuitive graphical user interface, AI-powered automation, and automated code generation, the ACS empowers users to focus on their core competencies, accelerating time-to-market and reducing development costs.



### Features

- > Built on DAVE™ (Digital Application Virtual Engineer)
- > Simplifies the development on Infineon's AURIX™ microcontrollers by combining a code editor, compiler, debugger, and graphical peripheral configuration tool
- > Accelerates evaluation and development, eliminating manual errors and upkeep through its automatic code generation and powerful hardware resource manager
- > The free, Eclipse based ACS IDE integrates a GNU open source C compiler for the AURIX™ TriCore™ architecture, a TCF open source debugger, a GUI driven code generation plug in, and a hardware resource solver.
- > Every ACS project uses built in AURIX™ low level drivers covering peripheral initialization, configuration, events, I/O handling, and runtime operation—no separate installation required.
- > ACS APPs are use case oriented components on top of the low level drivers. They are GUI configurable, manage dependencies, connect via signals and events, and can consume and configure resources from other APPs.

### Competitive advantage

- > All-in-one, free-of-charge tool, combining IDE, GUI based configurator, hardware resource manager, code generator, compiler and debugger
- > Simplifies complex workflows, making the development process faster, intuitive and efficient, reducing development time

### Benefits

- > Accelerates time-to-market
- > Reduces development costs
- > Empowers users to focus on their competencies

### Target applications

- > Optimizing and simplifying your work with Infineon's AURIX™ microcontrollers.

### Product collaterals / Online support

[Product page](#)